

**Claims after this response:**

1(Currently Amended). A packaged die comprising:

a die pad having a die having an electrical circuit thereon attached thereto;

a plurality of leads arranged around said die pad, at least one of said leads being connected to said die;

a power ring comprising a conductor disposed between said leads and said die pad, at least one power connection on said die being connected to said power ring; and

a layer of encapsulating material covering said die, said die pad, said power ring, and said leads, said layer having a top surface, a bottom surface, and side surfaces, wherein each of said leads comprises a conductor having a portion thereof exposed on said bottom surface and wherein a portion of said conductor in said power ring is exposed on said bottom surface, wherein said exposed portions of each lead on said bottom surface are arranged such that each lead is connected to a corresponding one of said side surfaces and wherein said leads connected to at least one of said side surfaces comprise a first one of said leads that has said exposed portion at different distances from that side surface than said exposed portion of a second one of said leads connected to that side surface.

2(Original). The packaged die of Claim 1 wherein said exposed portions of said conductors further comprise solder balls.

3(Original). The packaged die of Claim 1 wherein said die pad, said leads, and said power ring each extend to at least one of said side surfaces.

4(Original). The packaged die of Claim 1 wherein each of said leads comprises a conductor having a portion thereof that is not exposed on said bottom surface and wherein a portion of said conductor in said power ring is not exposed on said bottom surface.